CORRESPONDING TO RoHS DIRECTIVE 對應RoHS指令

(EU RoHS Directive 2011/65/EU)

Product Name 產品名稱		Conductive Polymer Aluminum Solid Electrolytic Capacitors 導電式高分子固態鋁電解電容器		Conductive Polymer Hybrid Aluminum Electrolytic Capacitors 導電式高分子混合型鋁電解電容器	
Type 類型		Chip type 貼片式	Radial lead type 引線式	Chip type 貼片式	Radial lead type 引線式
RoHS compliant RoHS符合性		Yes 符合	Yes 符合	Yes 符合	Yes 符合
RoHS restricted substances 限制有害物質	The portion of the components 產品的部分特性	Sn plating 鍍錫引線		Sn plating 鍍錫引線	
Lead (Pb) 鉛	Plating on terminals 引線鍍層				
	Construction of terminals 引線結構	Fe/Cu/Sn 鍍錫銅包鐵線		Fe/Cu/Sn 鍍錫銅包鐵線	
	Resistance to soldering heat 耐焊接熱	Please refer to page 22 "Soldering Conditions" 請查閱第22頁的 “焊接條件”	Correspondence to 265°C wave soldering condition 對應265°C的波峰焊接條件	Please refer to page 22 "Soldering Conditions" 請查閱第22頁的 “焊接條件”	Correspondence to 265°C wave soldering condition 對應265°C的波峰焊接條件
	Solderability 可焊性	No difference with Sn-Pb 與鉛錫線相同		No difference with Sn-Pb 與鉛錫線相同	
	Tensile strength 抗拉强度	No difference with Sn-Pb 與鉛錫線相同		No difference with Sn-Pb 與鉛錫線相同	
Hexavalent chromium (Cr VI) 六價鉻		Not detected 未檢出		Not detected 未檢出	
Mercury (Hg) 汞					
Cadmium (Cd) 鎘					
PBBs 多溴聯苯					
PBDEs 多溴二苯醚					
HBDD 六溴環十二烷					
DBP 鄰苯二甲酸二丁酯					
BBP 鄰苯二甲酸丁苄酯					
DEHP 鄰苯二甲酸雙（2-乙基己）酯					
Identification for RoHS compliance products RoHS符合性產品的識別		Added "Pb free" and "RoHS" symbol on inner and outer carton label 外箱和內箱上印有“PB free”和“RoHS”符號標識		Added "Pb free" and "RoHS" symbol on inner and outer carton label 外箱和內箱上印有“PB free”和“RoHS”符號標識	
MSL Level 濕度敏感水平 (IPC/JEDEC J-STD-020C)		Not applicable 不適用		Not applicable 不適用	

Aluminum Electrolytic Capacitors 鋁電解電容器		Chip type 貼片式	Radial lead type 引線式	Snap-in terminal type 導箔式
RoHS compliant RoHS符合性		Yes 符合	Yes 符合	Yes 符合
RoHS restricted substances 限制有害物質	The portion of the components 產品的部分特性	Change plating from Sn-Pb to Sn 將鍍鉛錫合金變更為鍍錫		
Lead (Pb) 鉛	Plating on terminals 引線鍍層			
	Construction of terminals 引線結構	Fe/Cu/Sn 鍍錫銅包鐵線		
		• Plating thickness 8~10μm • Plating type matte • No heat treatment after plating • 鍍錫層厚度8~10μm • 鍍錫層類型不光滑 • 鍍錫後無熱處理		• Plating thickness 6~10μm • Plating type matte • No heat treatment after plating • 鍍錫層厚度6~10μm • 鍍錫層類型不光滑 • 鍍錫後無熱處理
	Insulating sleeve 膠管	No used 不使用	Replace PVC with PET (where customer designated) 將PVC更換為PET（若客戶指定）	
	Resistance to soldering heat 耐焊接熱	Please refer to page 23 "Soldering Conditions" 請查閱第23頁的 “焊接條件”	Correspondence to 260°C wave soldering condition 對應260°C的波峰焊接條件	
	Solderability 可焊性	No difference with Sn-Pb 與鉛錫線相同		
	Tensile strength 抗拉强度	No difference with Sn-Pb 與鉛錫線相同		
Hexavalent chromium (Cr VI) 六價鉻		Not detected 未檢出		
Mercury (Hg) 汞				
Cadmium (Cd) 鎘				
PBBs 多溴聯苯				
PBDEs 多溴二苯醚				
HBDD 六溴環十二烷				
DBP 鄰苯二甲酸二丁酯				
BBP 鄰苯二甲酸丁苄酯				
DEHP 鄰苯二甲酸雙（2-乙基己）酯				
Identification for RoHS compliance products RoHS符合性產品的識別		Added "Pb free" and "RoHS" symbol on inner and outer carton label 外箱和內箱上印有“PB free”和“RoHS”符號標識		
MSL Level 濕度敏感水平 (IPC/JEDEC J-STD-020C)		Not applicable 不適用		

Note: All design and specifications are for reference only and is subject to change without prior notice. If any doubt about safety for your application, please contact us immediately for technical assistance before purchase.

注：以上所提供的設計及特性參數僅供參考，任何修改不作預先通知。如果在使用上有疑問，請在採購前與我們聯繫，以便提供技術上的協助。

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